



YETDA INDUSTRY LTD.

Technical Data Sheet

MODEL NO : I3535A4P-M

3535 Package 3.45*3.45mm Chip LEDs

Features :

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

Applications :

- Lighting
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

| Dice material | Emitted color | Lens Color |
|---------------|---------------|-------------|
| GaAIAs | Infrared | Water Clear |

Electrical/Optical Characteristics(Ta=25°C)

| Parameter | Test Condition | Symbol | Value | | | Unit |
|-------------------------------------|-----------------------|----------------|-------|-----|-----|------|
| | | | Min | Typ | Max | |
| Forward voltage | I _F =350mA | V _F | | 1.5 | 2.0 | V |
| Wavelength | I _F =350mA | Wld | | 850 | | nm |
| Total Radiated Power | I _F =350mA | P _D | | 300 | | mW |
| Viewing angle at 50% I _v | I _F =350mA | 2θ 1/2 | -- | 120 | -- | Deg |
| Reverse current | V _r =5V | I _R | -- | - | 10 | μA |

Absolute Maximum Ratings(Ta=25°C)

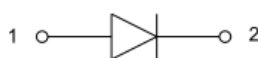
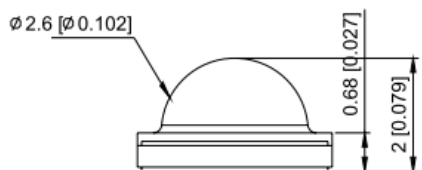
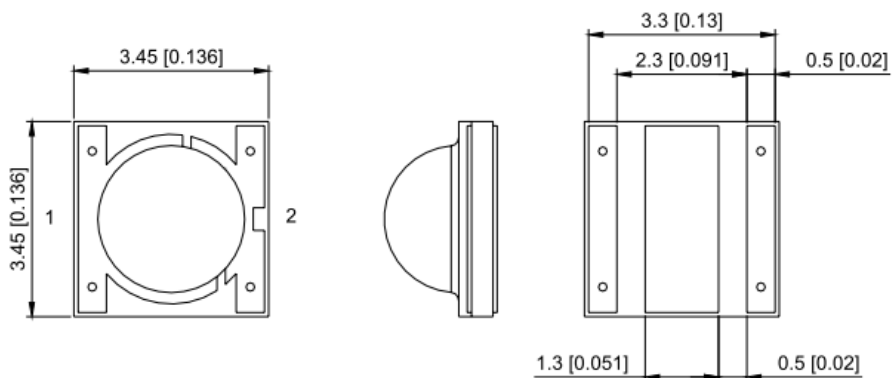
| Parameter | Symbol | Value | Unit |
|--|------------------|-----------|------|
| | | White | |
| Power dissipation | P _d | 2 | W |
| DC Forward current | I _F | 1 | A |
| Reverse voltage | V _R | 5 | V |
| Operating temperature range | T _{opr} | -40 ~+85 | °C |
| Storage temperature range | T _{stg} | -40 ~+100 | °C |
| Peak puls ng current (1/8 duty f=1kHz) | I _{FP} | 1500 | mA |

2017JAN20Y

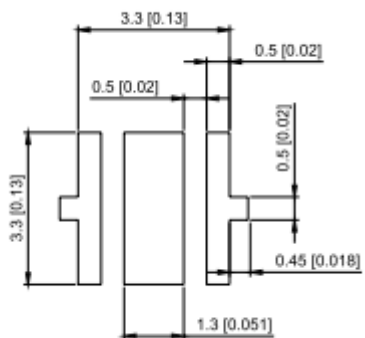


YETDA INDUSTRY LTD.

PACKAGING DIMENSIONS

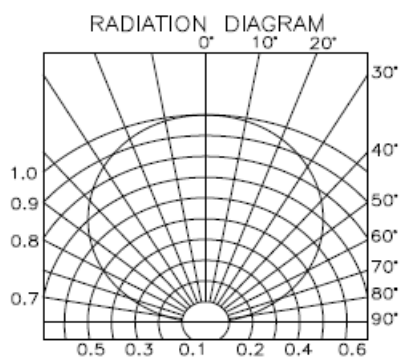
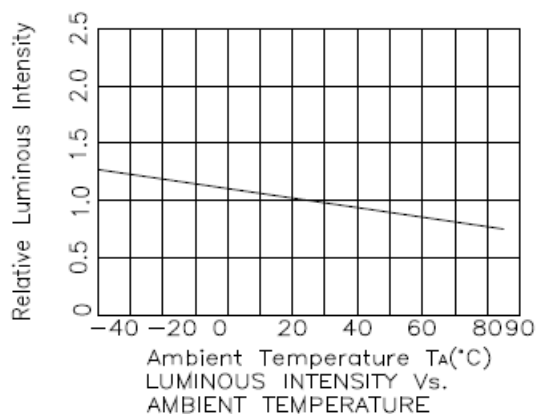
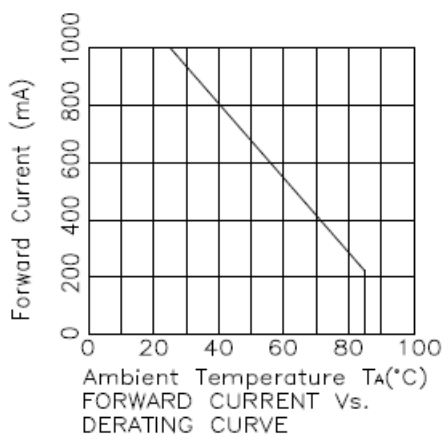
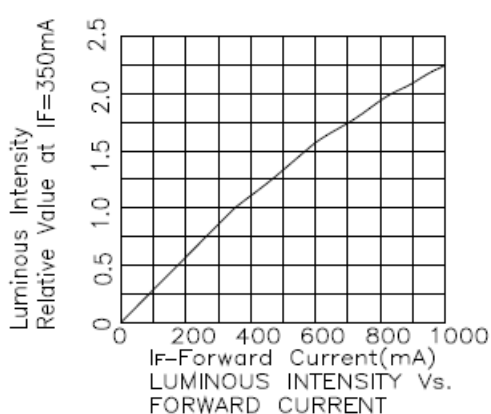
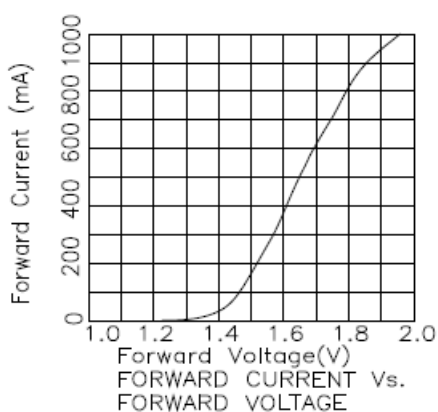
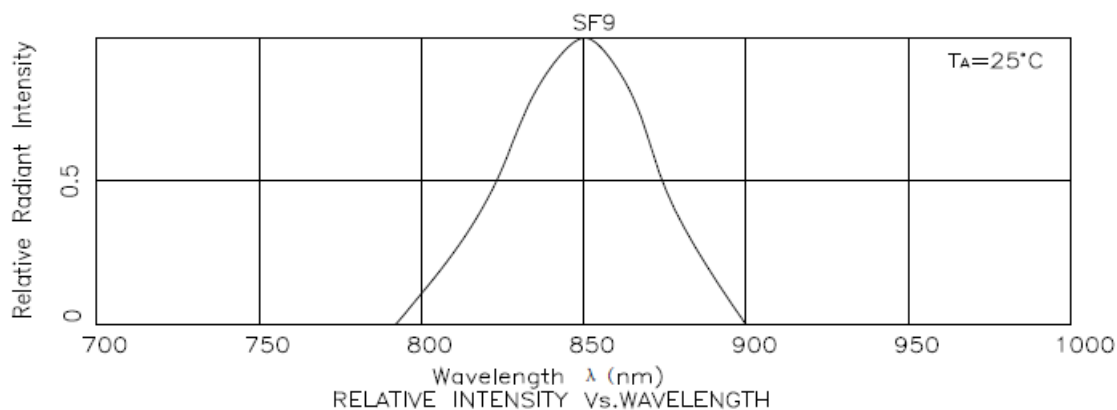


Recommended soldering pattern





YETDA INDUSTRY LTD.





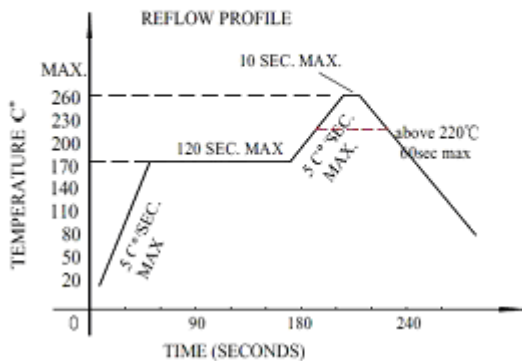
YETDA INDUSTRY LTD.

| |
|--|
| Precautions For Use : |
| Over - current - proof |
| Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen) |
| Storage |
| 1. The operation of temperature and R.H. are : 5°C ~30°C , 60%R.H. Max. |
| 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating reagent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date) . |
| 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : 60°C±5°C for 15hrs. |

■ Reflow Temp/Time

■ Temperature-profile (Surface of circuit board)

Use the following conditions shown in the figure.



NOTES:

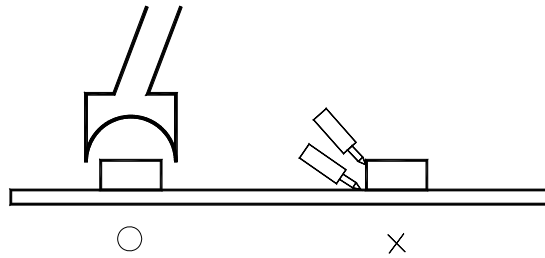
1. We recommend the reflow temperature 245°C(±5°C).the maximum soldering temperature should be limited to 260°C.
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter (+10°C → -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .



YETDA INDUSTRY LTD.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.

Dimensions of Tape (Unit: mm)

